

MICROSCOPY TODAY

JANUARY/FEBRUARY 2002

ISSUE #02-1



Break Through the Barriers

As technology advances, so does the number of barriers you face in analyzing and controlling deep submicron structures and processes. Today's samples are more complex and require a broad range of analytical techniques for thorough characterization. You need high resolution. Compromised results are not an option. You need to do and see more in less time.

FEI's unrivaled suite of 3D Structural Process Management™ solutions gives you total control and a winning edge for improving your time to results, increasing your efficiency, and improving your operation's bottom line—it's why the world's technology leaders come to us to help them through the technology shifts they face each and every day.

Advanced FIB, SEM, TEM, and DualBeam™ tools are at the heart of Structural Process Management solutions from FEI.

Structural Diagnostics™

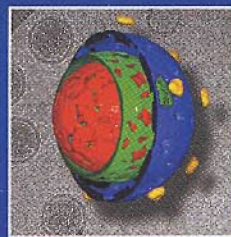
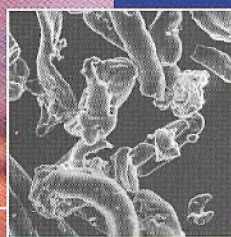
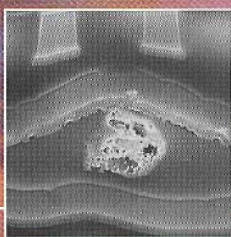
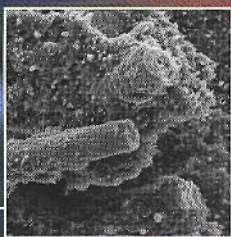
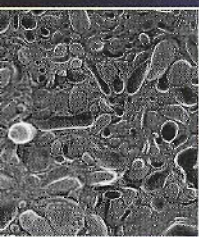
Structural Modification™

Structural NanoFabrication™

Structural Biology

Talk to us and discover how 3D Structural Process Management™ solutions from FEI can help you break through today's deep submicron and technology barriers.

Life Science
Material Science
Microelectronics



**Take Control with 3D
Structural Process Management™**

www.feicompany.com
sales@feico.com